

# ISSP2007 EXHIBIT

ISSP2007 Committee,  
The Vacuum Society of Japan

The ISSP Panel Exhibit\*) will be held in conjunction with The 9th International Symposium on Sputtering and Plasma Processes (ISSP2007) at the Kanazawa Kokusai Hotel from June 6 to 8, 2007. It will feature the broad spectrum of equipment, instruments, materials, systems, services, etc. for sputtering and plasma processes. At the last Exhibit, ISSP2005, 22 companies exhibited their offerings, and exchanged the information with over 300 attendees. This is the best opportunity for you to present, face-to-face, your products and services to a vital market. The Panel Exhibit will be opened parallel to ISSP2007 poster presentation at the same room. The ISSP2007 committee requests your company to attend this exhibition as an exhibitor. The up-to-date information can be seen at our web site: <http://issp2007.org/>. Please don't miss the terrific opportunity!

*Your presentation at the technical session of the symposium is strongly recommended as well as the panel exhibit, which is expected to dramatically improve the impact of your company.* (In this case, please apply as a normal presenting author.)

## Exhibit Details

### [Scope]

Process equipment (sputtering, evaporation, MBE, CVD, etching, etc.)  
Analyzer, controller, and measurement apparatus  
Related materials and components (Sputtering target, etc.)

### [Location and term]

Kanazawa Kokusai Hotel,  
Exhibit: From 17:00 June 6 to 14:00 June 8, 2007 (Symposium: From 10:00 June 6 to 14:00 June 8)

### [Exhibit fee]

¥ 120,000/unit (Japanese yen)  
(Including the exhibit fee ¥100,000 and the registration fee ¥20,000)

### [Special favor]

- \*The exhibitor can show one-page, monochrome, and camera-ready advertisement on the proceedings for free. Please tolerate that the printing quality is not so high grade.
- \*We prepare a link to your home site on our web page, <http://issp2007.org/>, according to your request.
- \*In accordance with the request of exhibitor, an automatic CM slide presentation by Powerpoint (without sound, 30sec/company, no page limit) will be available during the break time of oral session. (Details will be informed later.)

### [How to apply]

Please fill the application form and send it to the committee member by email.  
Please attach the banner image file of your company, in case that you wish to make link point of your company's home page on the ISSP2007 web site.

#### **Deadline: April 27, 2007**

If you want to apply the one-page advertisement on the proceedings, please send a PDF file or a paper-printed copy to the committee member (see the end of this article).

---

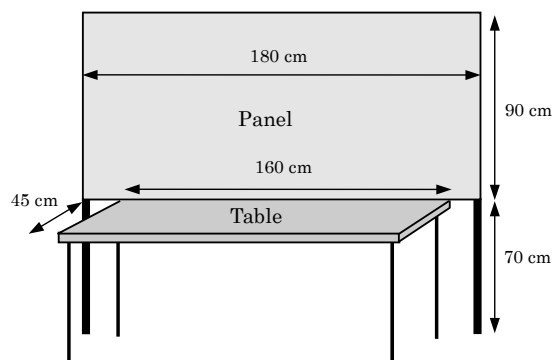
\*) Be careful that the ISSP2007 Exhibit is different from the Manufacturer's Presentation of ISSP2007 which is a technical presentation made by invited manufacturer.

## [Policy]

- \*Description language is English.
- \*At least one person is required to explain the panels. He/she is entitled to attend all the session of ISSP2007 for free.
- \*For extra two persons of exhibitor, the registration fee is ¥20,000 per person. From the 4<sup>th</sup> person and up, please register as a normal participant.
- \*The carriage of all the exhibiting materials is to be made by yourself.
- \*Don't remove the panel before the closing of ISSP2007.

## [Configuration]

- \*One unit of exhibition space consists of a panel of about 180 cm (width) × 90 cm (height) and a desk of 160 cm (width) × 45 cm (depth) × 70 cm (height).
- \*The total weight of exhibiting materials on the desk should be less than 10 kg.
- \*If you need more space, you may use multiple exhibition units by paying additional fee. The acceptance will be informed later.
- \*Utilities of electrical power are available for personal computer use. It, however, is limited to 2 A (AC100 V).
- \*If you would like to make any special exhibition, please consult with us.



## [Questions and Application]

ISSP2007 Secretariat

Advanced Material Science Center, Kanazawa Institute of Technology

3-1, Yatsukaho, Hakusan, Ishikawa 924-0838, JAPAN

TEL: +81-76-274-9250 FAX: +81-76-274-9251

E-mail: [exhibit@issp2007.org](mailto:exhibit@issp2007.org)

## Exhibitors of the Past ISSP Exhibit

- |   |  |
|---|--|
| <ul style="list-style-type: none"><li>• Advanced Energy Japan</li><li>• AIMEC Corp.</li><li>• ASTECH Corp.</li><li>• BOC Coating Technology</li><li>• Canon ANELVA Corp.</li><li>• ENI JAPAN Ltd.</li><li>• Fraunhofer-Institut für Elektronenstrahl- und Plasmatechnik</li><li>• FTS Corp.</li><li>• Gencoa Ltd.</li><li>• Hakuto Co., Ltd.</li><li>• HITACHI ZOSEN Corp.</li><li>• Hüttinger Elektronik GmbH</li><li>• JAPAN ENERGY Corp.</li><li>• JEOL Ltd.</li><li>• Kurt J. Lesker Company</li><li>• Landmark Technology Corp.</li><li>• MARUBUN Corp.</li><li>• Matsubo Co., Ltd.</li><li>• MITSUBISHI MATERIALS Corp.</li><li>• Oerlikon Japan Co., Ltd.</li><li>• Oerlikon Leybold Vacuum Japan Co., Ltd.</li><li>• NANO SCIENCE CORPORATION</li></ul> | <ul style="list-style-type: none"><li>• NANOMETRICS JAPAN</li><li>• NIHON VEECO K. K.</li><li>• NIPPON MINING &amp; METALS CO., LTD.</li><li>• NOA SYSTEMS Inc.</li><li>• NTT AFTY Corp.</li><li>• OXFORD INSTRUMENTS</li><li>• PEGASUS Software Inc.</li><li>• SAES GETTERS JAPAN Co., Ltd.</li><li>• Sanyu Electron Co., Ltd.</li><li>• Science Technology Co., Ltd.</li><li>• SHINCRON Co., Ltd.</li><li>• SHOWA SHINKU Co., Ltd.</li><li>• Singulus Technologies AG</li><li>• Sputtered Films, Inc.</li><li>• TDY INC.</li><li>• THERMO RIKO CO., LTD.</li><li>• ULVAC CRYOGENICS INC.</li><li>• ULVAC JAPAN, Ltd.</li><li>• ULVAC-PHI, INC.</li><li>• UNIVERSAL SYSTEMS Co., Ltd.</li><li>• VACUUM METALLUGICAL Co., Ltd.</li><li>• VIC International Co., Ltd.</li></ul> |
|---|--|